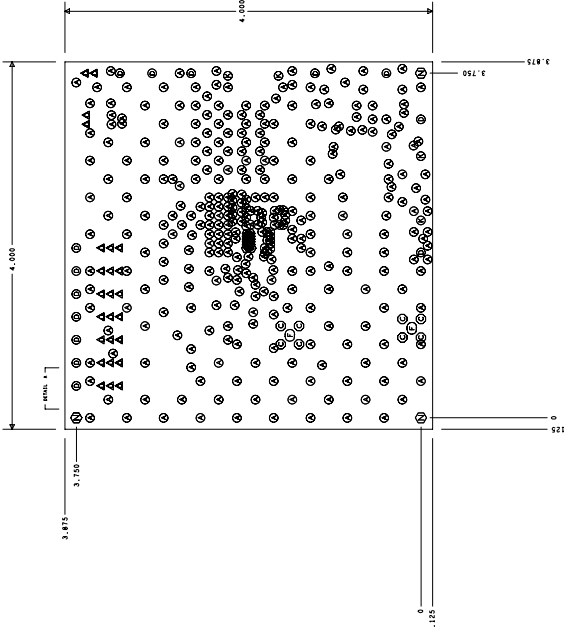


.062
+/-10%

Layer Stacking
Scale: None

- NOTES: UNLESS OTHERWISE SPECIFIED.
1. BOARD IS VIEWED FROM LAYER 1 (PRIMARY SIDE). TOTAL CONDUCTOR LAYERS ARE 4.
 2. THIS DRAWING ALSO EXISTS ON ELECTRONIC MEDIA.
 3. MANUFACTURE/FABRICATE TO MEET EU RoHS DIRECTIVE. ALL MATERIALS AND SOLDERMASK TO BE COMPLIANT TO EU RoHS DIRECTIVE 2002/95/EC LAMINATE AND RESIN MATERIAL PARAMETERS
Tg > 170 C
Td > 294 C
 4. FINISH:
ELECTROLESS NICKEL/GOLD(ENIG)PLATING IS TO BE USED. 3-8 uin GOLD OVER 100uin NICKEL.
 5. SOLDERMASK SHALL BE LPI(BLUE)OVER BARE COPPER, 0.0005" -0.002" THICK, AND CONFORM TO THE LATEST REVISION OF IPC-SM-840. SOLDERMASK IS ALLOWED IN VIA HOLES INTO WHICH NO COMPONENT LEAD IS SOLDERED.
 6. CONDUCTOR WIDTH AND SPACING:
THE NOMINAL CONDUCTOR WIDTH AND SPACING ON FINISHED BOARD IS:
WIDTH 0.010"
SPACING 0.007"
 7. SILKSCREEN SHALL BE WHITE NONCONDUCTIVE EPOXY INK, AND SHALL NOT APPEAR ON ANY PADS OR MOUNTING HOLES.
 8. PRIOR TO BOARD FABRICATION, COMPARE GERBER DATA TO SUPPLIED IPC-D-356A NET LIST. REPORT ALL DISCREPANCIES.

DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
⊙	8.0	PLATED	17
⊙	10.0	PLATED	332
⊙	37.0	PLATED	8
⊙	40.0	PLATED	14
▲	41.0	PLATED	25
⊗	65.0	PLATED	2
⊙	100.0	PLATED	4
⊗	128.0	NON-PLATED	3
TOTAL			405



DETAIL A
LAYER COPPER SHALL CONSIST OF 2 OZ. COPPER WITH SHIMMS ON EACH LAYER

Drawn By: J. De Maio	Date Drawn: 02-03-09	Engineer: S. Laur
Released By:	Date Released:	ISL95210 EVAL1Z Fabrication Drawing
Updated By:	Date Updated:	MASK# HDKW ID
intertecsi		REV. B
FILENAME: ISL95210_eval1z_b		SHEET 1 of 1